

ChipMOS TECHNOLOGIES [IMOS]



Safe Harbor Notice

- ❖ Certain statements contained in this presentation may be viewed as forward-looking statements within the meaning of Section 27A of the U.S. Securities Act of 1933, as amended, and Section 21E of the U.S. Securities Exchange Act of 1934, as amended.
- ❖ Such forward-looking statements involve known and unknown risks, uncertainties and other factors, which may cause the actual performance, financial condition or results of operations of the Company to be materially different from any future performance, financial condition or results of operations implied by such forward- looking statements. Further information regarding these risks, uncertainties and other factors is included in the Company most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the “SEC”) and in the Company’s other filings with the SEC.
- ❖ Financial figures contained in this presentation have been converted from NT\$ to US\$ using an exchange rate of US\$1 = NT\$30.36 as of June 30, 2008.

Investment Highlights

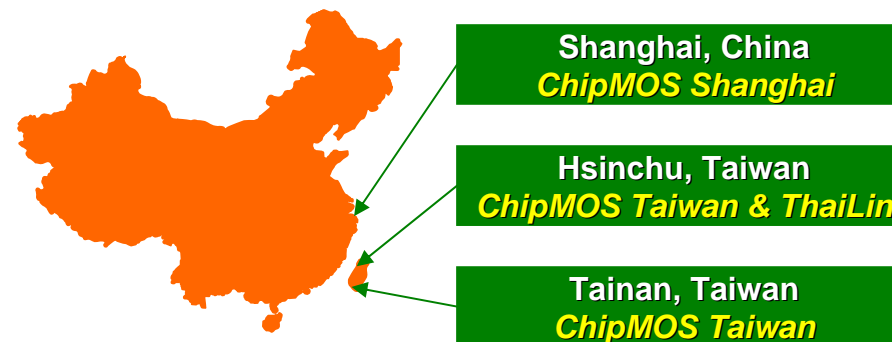
- Well-positioned in fast-growing segments of the Semiconductor Assembly and Test Services (SATS) industry
 - *Strong growth with increasing outsource of DRAM and flash market*
- A leading SATS provider with a demonstrated track record, strong earnings capability and experienced management team
- Positioned to capitalize on geographic location in the electronics supply chain in Taiwan and China
- Addition of new tier-1 customers and long-term contracts drives revenue & profit growth while reducing excess capacity risk





ChipMOS Introduction

Overview

- ❑ Established In: August 2000
- ❑ Headquarters: Hsinchu, Taiwan
- ❑ Ticker/Listing: IMOS / NASDAQ Global Select
- ❑ Index Member: NASDAQ Composite & NASDAQ Computer
- ❑ Market Cap.⁽¹⁾: US\$ 272 million
- ❑ Employees⁽²⁾: 6,050

Manufacturing Footprint in China & Taiwan



	Memory		LCD Driver Gold Bumping, Testing & Assembly	Mixed-Signal ⁽³⁾		Memory Module	
	Testing	Assembly		Testing	Assembly		
 Taiwan	✓	✓	✓			✓	✓
 Shanghai	✓	✓				✓	
 ThaiLin	✓			✓			
 ChipMOS TECHNOLOGIES (Bermuda) LTD.	✓	✓	✓	✓	✓	✓	✓

(1) As of June 30, 2008.

(2) As of June 30, 2008.

(3) Primarily FPD peripheral chips.

Product Mix Focused On High Growth Areas

- ❑ ChipMOS provides leading-edge semiconductor assembly and testing technologies to meet the requirements of high growth applications
- ❑ Focused product mix helps ChipMOS gain competitiveness on core technologies and cost-effectiveness

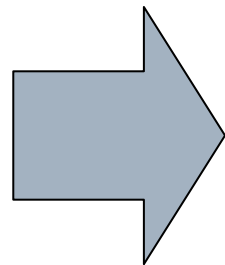
ChipMOS Core Technologies



DRAM **Flash (NOR/NAND)**

LCDD **Mixed-Signal**

Targeting On High Growth Applications



<p>Flat Panel Display</p> <ul style="list-style-type: none">- LCD driver IC- Mixed-signal (FPD peripheral ICs)- DRAM	<p>Mobile Devices</p> <ul style="list-style-type: none">- Flash- MCP- DRAM- LCD driver IC
<p>Home Media Center</p> <ul style="list-style-type: none">- DRAM (next driving force)- LCD driver IC- Mixed-signal ICs for Audio/Video	<p>Next Generation Mobile Computing</p> <ul style="list-style-type: none">- Flash (huge demand driven by instant booting – to replace hard drive as booting device & cache)- High density & low power consumption memory- LCD driver IC

Leading SATS Provider for Memory

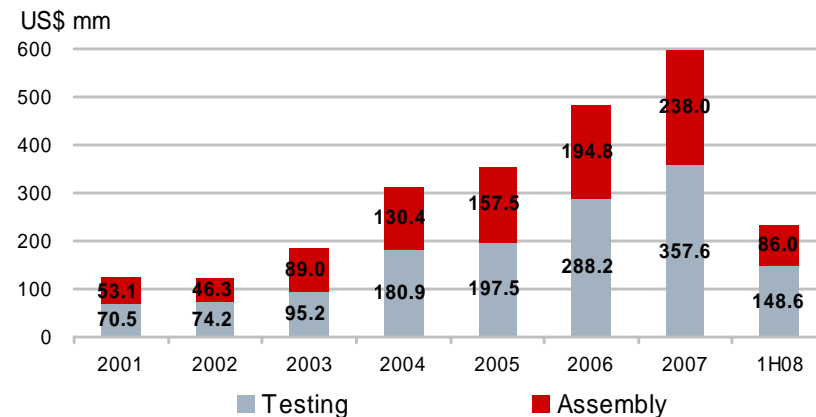
Capture Growth With Blue-Chip Clients and Outsourcing Trend

- ❑ Aim to maintain leadership in memory back-end capacity and technology service providing
- ❑ Long-term contracts with ProMOS till 2012 and with a leading NOR Flash provider in USA till 2012
- ❑ Technical expertise: Ability to test DDR II/III DRAM and 12” wafers assembly
- ❑ Equipment flexibility between DRAM, Flash, and other memory products

Key Customers Include Market Leaders



Memory Testing And Assembly Revenue



Leading SATS Provider for LCD Drivers

Sector Leader with Comprehensive Service Offering

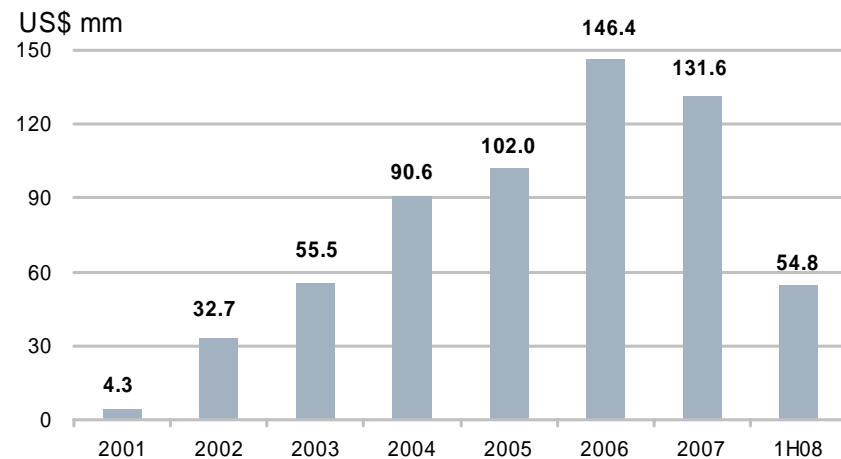
- Offering full range of services for LCD drivers and FPD chipsets including gold bumping and Tape-Carrier-Package (TCP), Chip-on-Film (COF) and Chip-on-Glass (COG) package types
- Leveraging technology expertise to provide complementary services for CMOS image sensors, fingerprint sensors and organic display products

Key Customers Include Two Major Players On L-T Contracts






Note: Highlighted clients reflect those with whom we have long-term contracts.

LCD And Other FPD Driver Testing And Assembly Revenue



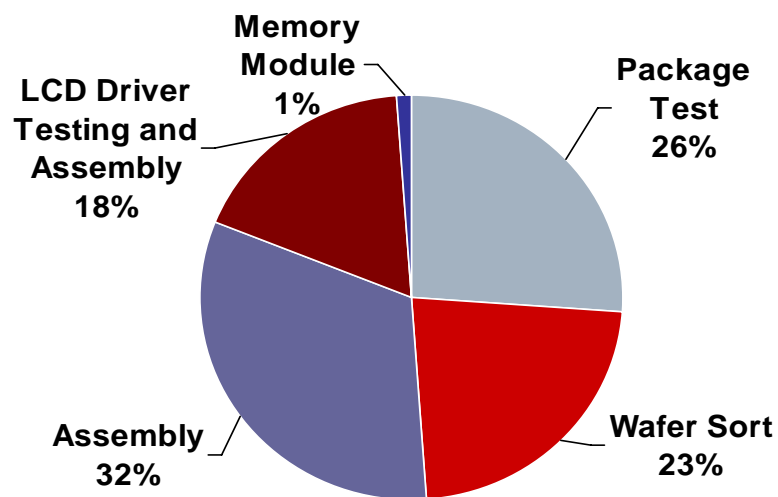
L-T Contracts Reducing Excess Capacity Risk

L-T Contracts Accounted for 46% of Current Capacity

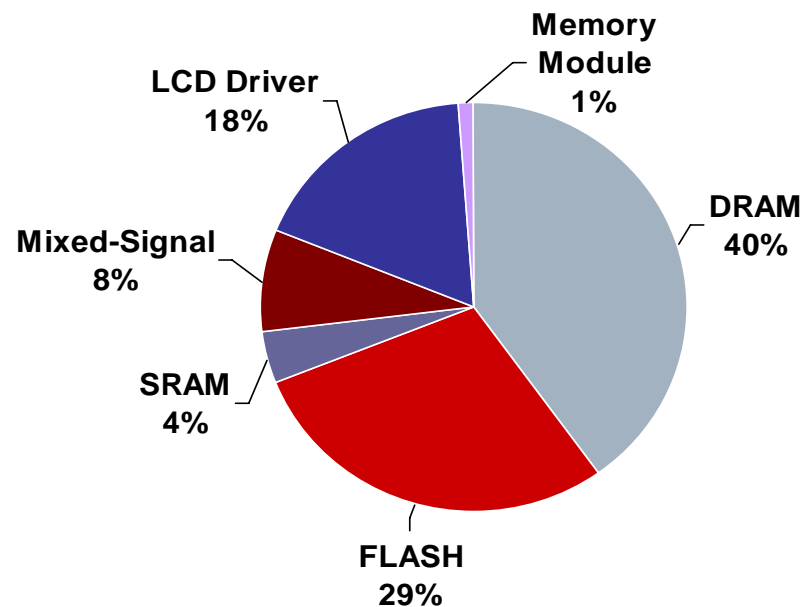
Customer	Product Type	Contract Expiration	Contract Type
 ProMOS TECHNOLOGIES	Memory	2012	Fix volume
Nor Flash Leader in USA	Memory	2012	Fix revenue
 NOVATEK	LCD	2008	Fix volume
 Himax	LCD	2008	Fix volume
Mixed-Signal Customer in USA	Mixed-Signal	2009	Fix revenue

Q2'08 Revenue Breakdown

By Manufacturing Segments



By Products

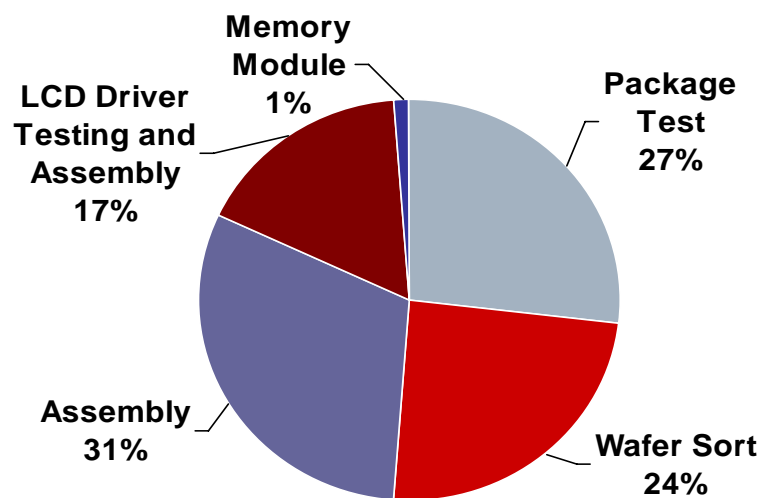


Top 10 Customers	
DRAM leader in USA	Macronix
Elite	NOR flash leader in USA
Fidelix	Novatek
Himax	Powerchip
ICSI	ProMOS

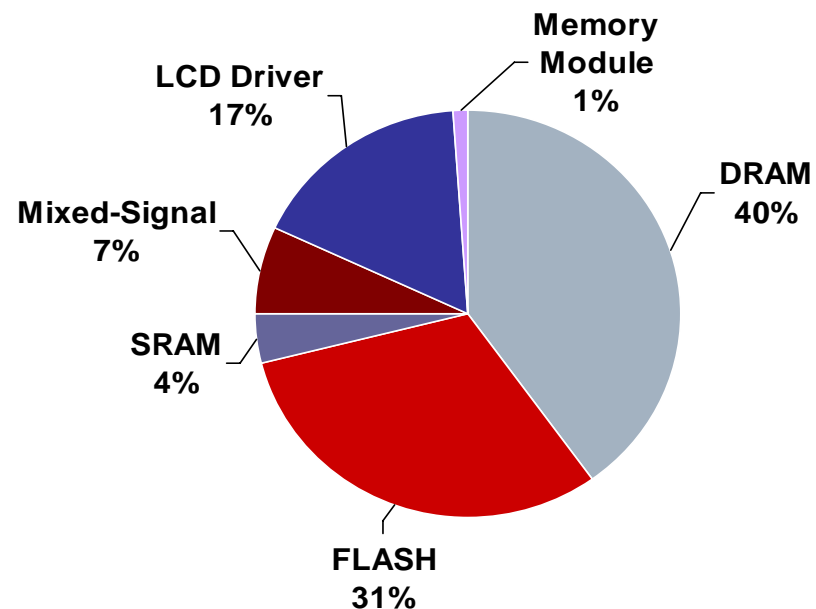
* Sorted by alphabetic order

1H'08 Revenue Breakdown

By Manufacturing Segments



By Products



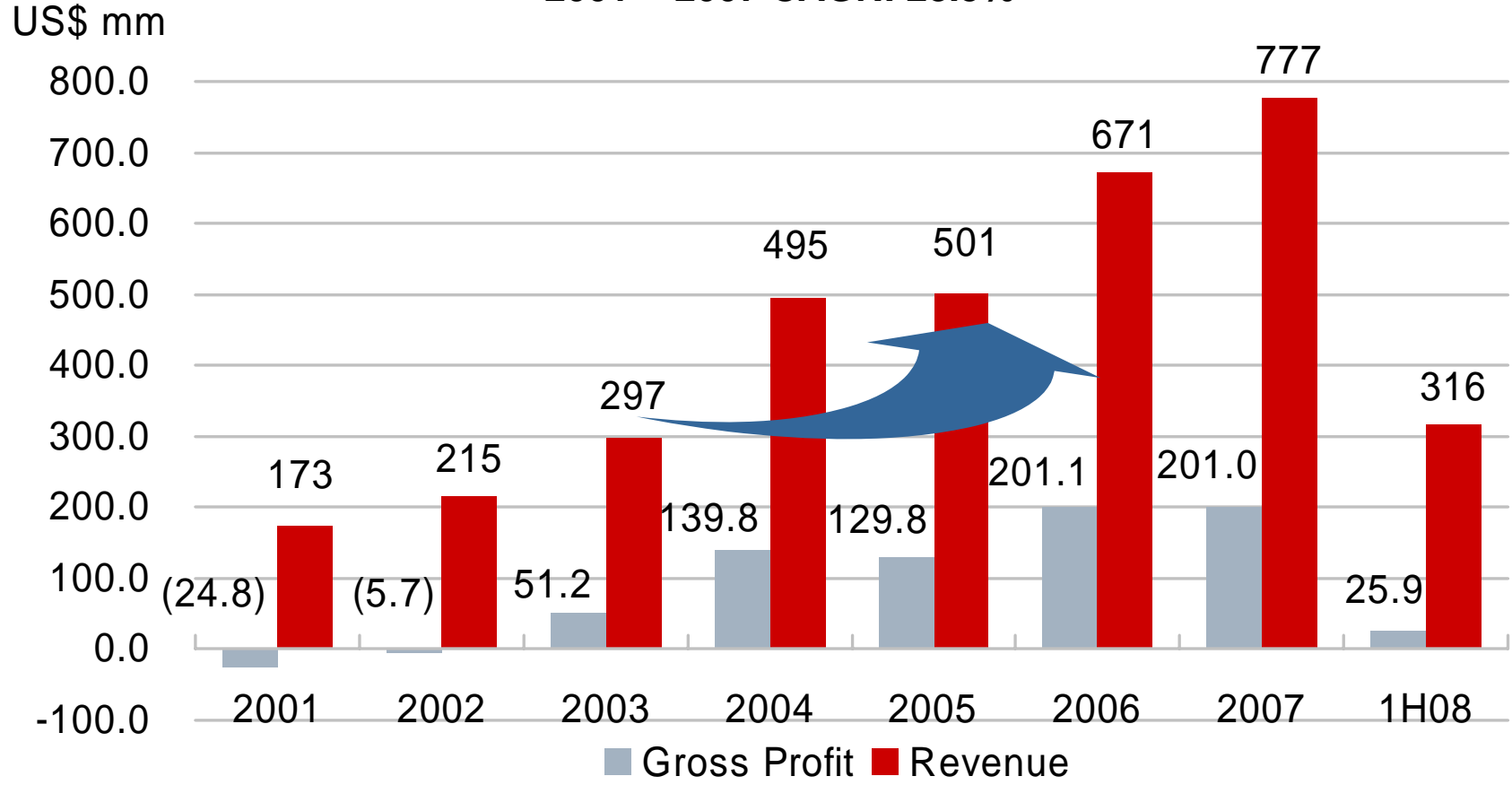
Top 10 Customers	
DRAM leader in USA	Macronix
Elite	NOR flash leader in USA
Himax	Novatek
ICSI	Powerchip
Leading PC peripheral chip provider in USA	ProMOS

* Sorted by alphabetic order

A Different SATS Model: Profit-Driven Growth

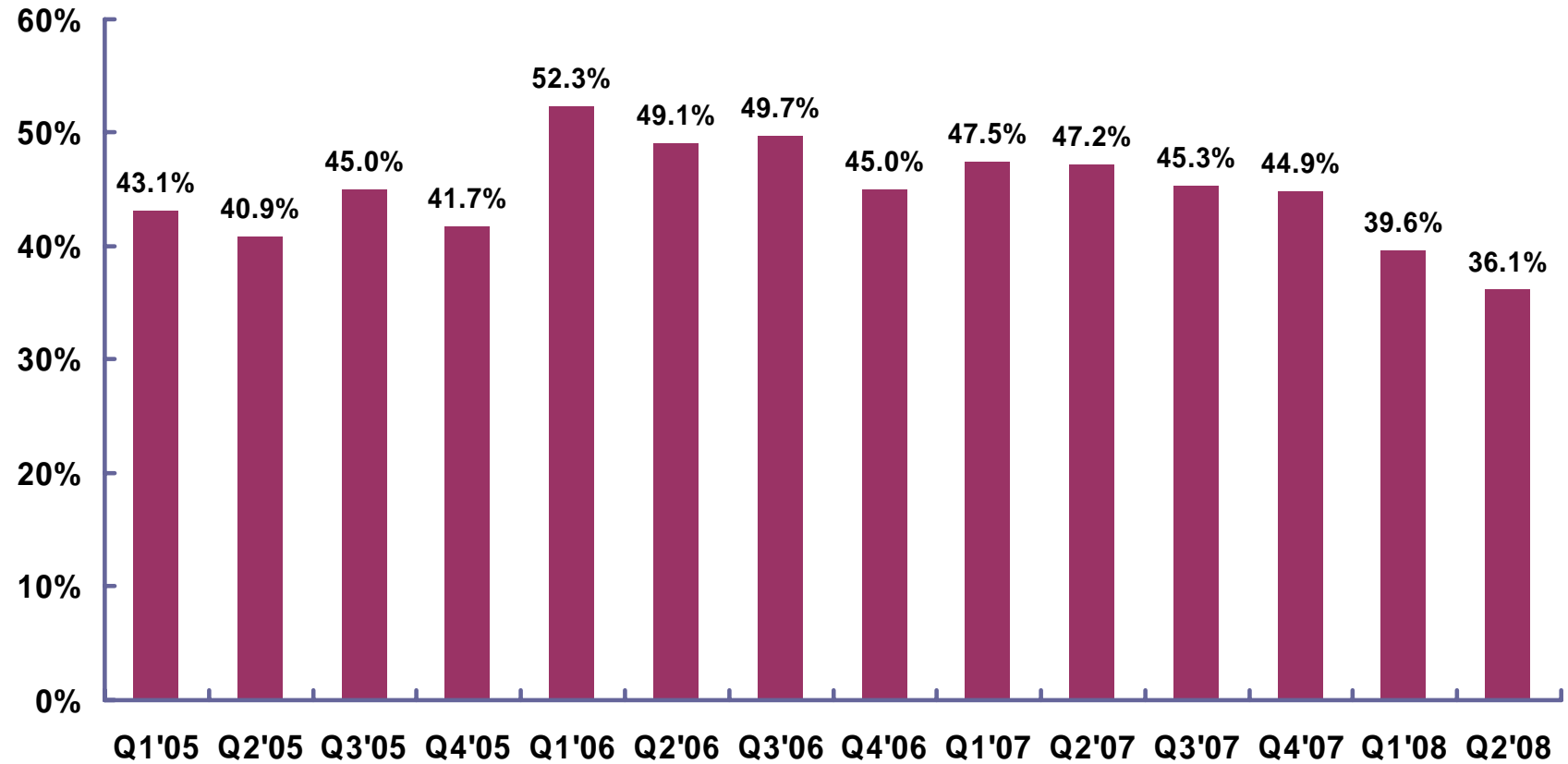
YoY Revenue Growth (US GAAP)

2001 - 2007 CAGR: 28.5%



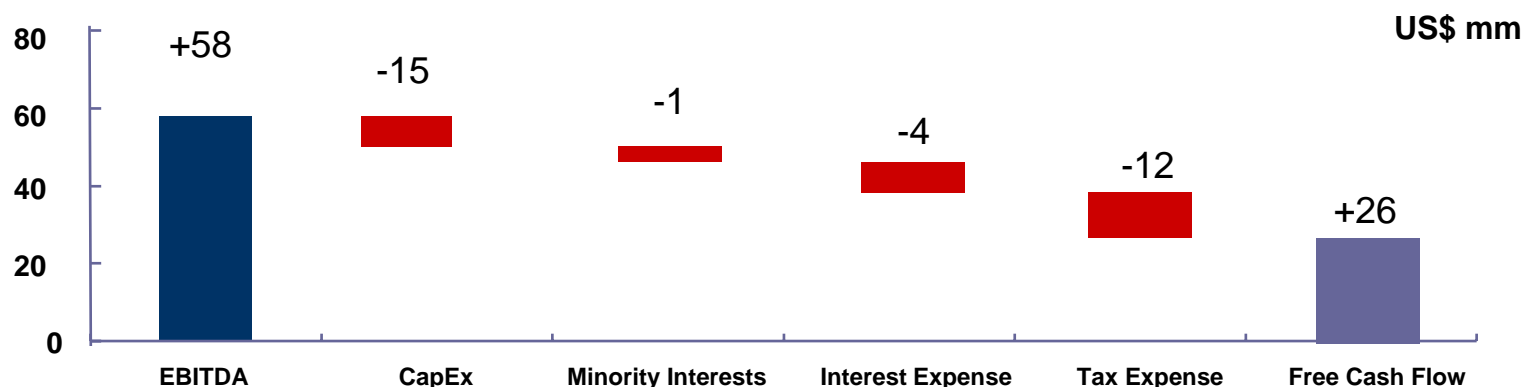
Stable EBITDA Performance

Historical EBITDA Margin (US GAAP)

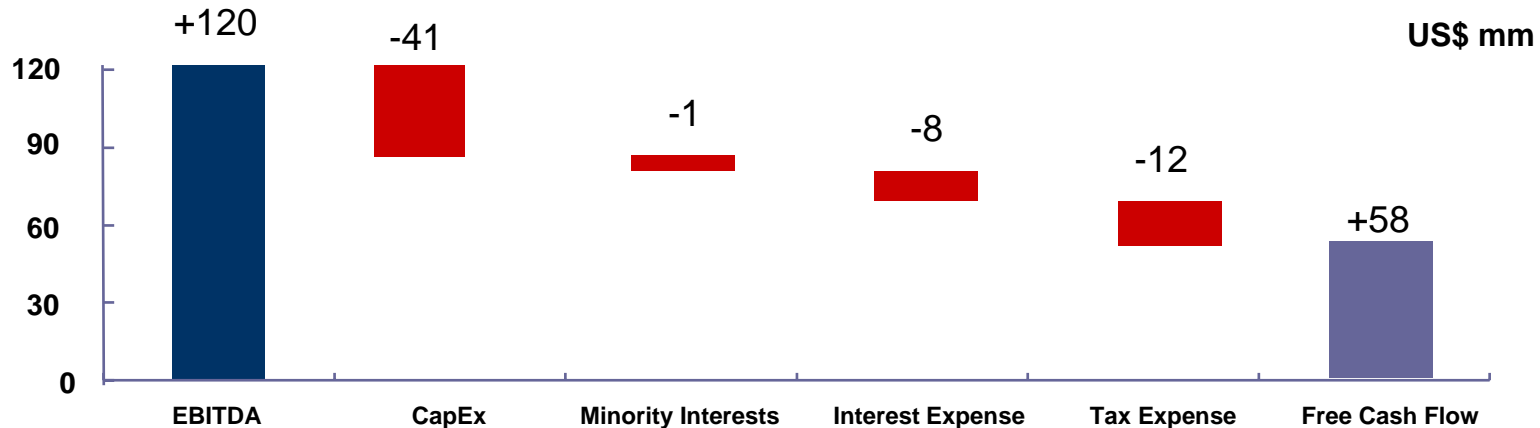


Free Cash Flow

2008 Q2 Free Cash Flow Reconciliation



2008 1H Free Cash Flow Reconciliation



□ Calculation based on Non GAAP numbers

3Q'08 Market Outlook

□ DRAM business

- The overall DRAM market visibility in following quarters remains limited.
- Our DRAM business is not recovering to last year levels reflecting slower output plan from DRAM makers and low market price due to weaker than expected PC demand in the second half of this year.
- Continued ASP pressure at backend side will be another key factor on our DRAM business performance in Q3

□ Flash business

- Growth of Mask ROM business will continue in Q3 based on the strong demand on our customer products.
- We expect to see significant growth of Mask ROM business in the second half of the year.

3Q'08 Market Outlook (cont'd)

□ LCD driver business

- Customers tend to give quick-turn orders in order to adjust their inventory levels in response to lower than expected panel demand in the second half of this year.
- Gold bumping business will maintain its growth momentum in the second half due to new customer programs.
- We still notice better demands from our customers in 4Q as compared to 3Q.

□ Mixed-signal business

- The new business development in mixed-signal segment is another key program to ChipMOS in year 2008.
- With customer base increase in PC peripheral IC segment, mixed-signal business is expected to maintain its growth in the second half.

3Q'08 Market Outlook (cont'd)

- ❑ We are confident to achieve over US\$100 million of positive free cash flow in the year of 2008.
- ❑ We have completed our investment obligation of US\$130 million for China project in early August.
- ❑ Combining our cash position and undrawn credit lines provided by banks, we have more than sufficient financial resources to face the debt due before end Q2'09.
- ❑ There is no urgent need for company to raise additional fund in any form from the market.